

DOCKET NO. 45475-00028
99-44653

PATENT APPLICATION

In re application of:

Jun Young Yang

Application No.

09/687,493

Filed:

October 13, 2000

For:

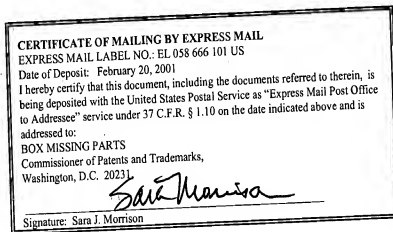
SEMICONDUCTOR PACKAGE HAVING IMPROVED
ADHESIVENESS AND GROUND BONDING

Group No.

2811

Examiner:

(Not Yet Known)



BOX MISSING PARTS
Assistant Commissioner for Patents
Washington, D.C. 20231

RESPONSE TO NOTICE TO FILE MISSING PARTS
OF NONPROVISIONAL APPLICATION FILED UNDER 37 CFR §1.53(b)
FILING DATE GRANTED

This is a response to the Notice of Missing Parts of Application - Filing Date Granted mailed
on November 27, 2000.